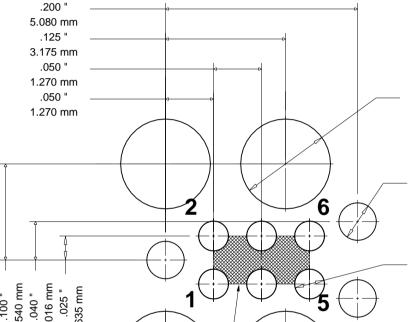
Notes:

- 1. Allow clearance for finger squeeze access from the two sides shown.
- 2. No tracks or vias in the shaded "KEEP OUT" AREA.
- 3. No other track or signal within .02" of any contact pad.
- 4. Do not allow solder paste on the contact pads It is essential to eliminate any hole in the solder paste-mask (solder stencil) layer. If this is not possible make the contact pads thru-hole with a finished hole size of .008" or less.
- 5. Leg and alignment holes may be plated and used as vias but ensure minimum finshed hole size meets specified tolerances.
- 6. To prevent purchasing confusion, please specify DNL in your BOM.

Allow finger access from this side

FOOTPRINT FOR TC2030-MCP PLUG-OF-NAILS (TM) CABLE

TC2030-MCP-FP



ZONE

REV

Ø.0935 "± .0030 Ø2.375 mm± .076 NON-PLATED THRU HOLE LEG LATCH HOLES

12/2/10

Ø.039 "±.003 Ø.991 mm+ .076 NON-PLATED THRU HOLE ALIGNMENT PIN HOLES

Ø.787 mm± .076 Ø.031 "± .003 CONDUCTIVE CONTACT PADS NO SOLDER PASTE

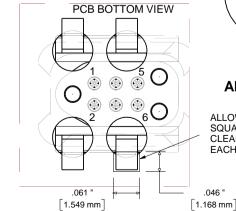
Microchip ICD / ICSP signals

Pin 1: MCLR / Vpp

Pin 2: Vdd Pin 3: GND

Pin 4: PGD (ICSPDAT) Pin 5: PGC (ICSPCLK)

Pin 6: Unused / LVP



Allow finger access from this side

"KEEP OUT" AREA

ALLOW A .061 X .046 SQUARE AREA OF CLEARANCE FOR **EACH FOOT**

Α	
SCALE	

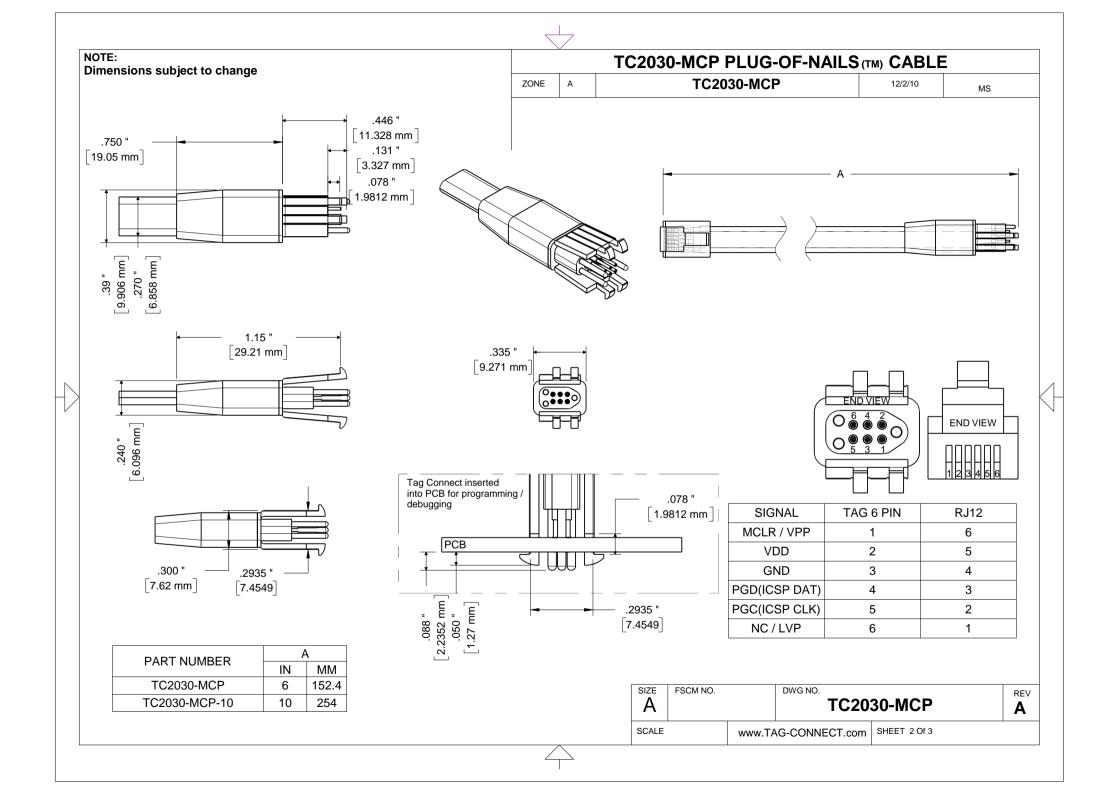
FSCM NO. **FOOTPRINT FOR**

TC2030-MCP-FP

REV Α

www.TAG-CONNECT.com

SHEET 1 Of 3



Layout Problems to Avoid

